

3.0x1.0 mm PHOTOTRANSISTOR

PRELIMINARY SPEC

Part Number: APECVA3010P3BT

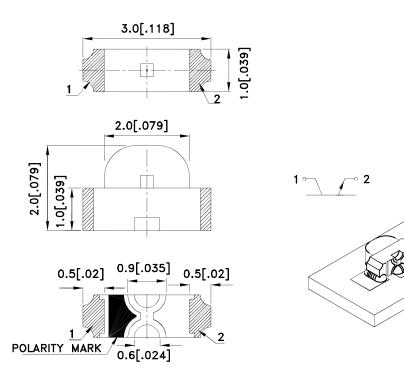
Features

- 3.0mmx1.0mm SMT LED, 2.0mm thickness.
- Mechanically and spectrally matched to the infrared emitting LED lamp.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

Made with NPN silicon phototansistor chips.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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REV NO: V.1 CHECKED: Allen Liu DATE: MAR/19/2009 DRAWN: S.P.Chen

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Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
VBR CEO	Collector-to-Emitter Breakdown Voltage	30			V	Ic=100uA Ee=0mW/c m³
VBR ECO	Emitter-to-Collector Breakdown Voltage	5			V	IE=100uA Ee=0mW/c m [*]
VCE (SAT)	Collector-to-Emitter Saturation Voltage			0.8	V	Ic=2mA Ee=20mW/c m²
I CEO	Collector Dark Current			100	nA	Vc=10V Ee=0mW/c m³
TR	Rise Time (10% to 90%)		15		us	VCE = 5V IC=1mA RL=1000Ω
TF	Fall Time (90% to 10%)		15		us	
I (ON)	On State Collector Current	0.2	0.8		mA	VcE = 5V Ee=1mW/c m ³ λ=940nm

Absolute Maximum Ratings at TA=25°C

Parameter	Max.Ratings			
Collector-to-Emitter Voltage	30V			
Emitter-to-Collector Voltage	5V			
Power Dissipation at (or below) 25°C Free Air Temperature	100mW			
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

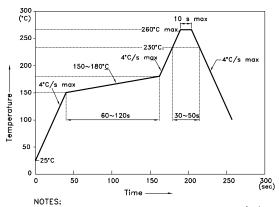
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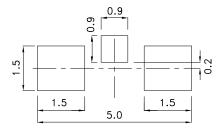
Reflow Soldering Profile For Lead-free SMT Process.



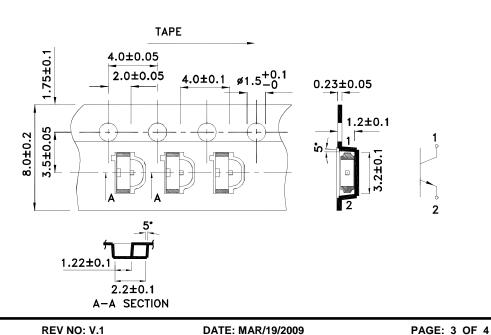
- 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- to high temperature.

 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Specifications (Units: mm)

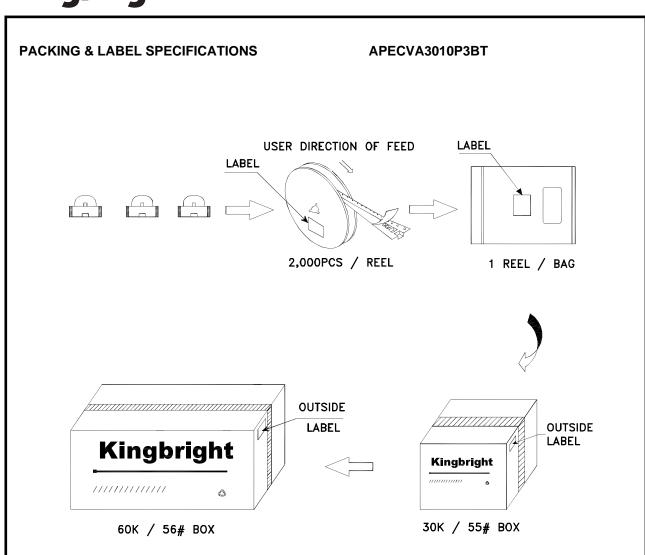


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